

**AMENDMENTS TO THE CLAIMS**

**Claim 1 (Previously cancelled)**

**Claim 2 (Currently amended):** The flexible board as set forth in claim 4, further comprising:

(f e) a first cover layer formed over a surface of said first ground layer; and

(g f) a second cover layer formed over a surface of said second ground layer.

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**Claim 3 (Original):** The flexible board as set forth in claim 2, further comprising electrically insulating adhesive layers sandwiched among said internal layer, said first and second ground layers, and said first and second cover layers.

**Claim 4 (Currently amended):** A flexible board comprising a ground line, said ground line comprising:

(a) an internal layer;

(b) a line formed in a first area of said internal layer, said line radiating unnecessary radiation;

(c) a first ground layer formed on an upper surface of said internal layer, said first ground layer disallowing radiation to pass therethrough; and

(d) a second ground layer formed on a lower surface of said internal layer, said second ground layer disallowing radiation to pass therethrough; and

~~(e) a ground line formed in a second area except said first area in said internal layer.~~

**Claim 5 (Previously amended):** The flexible board as set forth in claim 4, wherein a plurality of throughholes is formed throughout said first ground layer, said internal layer, and said second ground layer.

**Claim 6 (Original):** The flexible board as set forth in claim 4, wherein a plurality of throughholes is formed throughout said first ground layer, said ground line, and said second ground layer, said through-holes electrically connecting said first ground layer, said ground line, and said second ground layer to one another.

**Claim 7 (Previously Cancelled)**

**Claim 8 (Currently amended):** The method as set forth in claim 10, further comprising the steps of:

(e-d) covering a surface of said first ground layer with a first cover layer; and

(f e) covering a surface of said second ground layer with a second cover layer.

**Claim 9 (Original):** The method as set forth in claim 8, further comprising the step of forming electrically insulating adhesive layers among said internal layer, said first and second ground layers, and said first and second cover layers.

**Claim 10 (Currently amended):** method of fabricating a flexible board, comprising the steps of forming a ground line by:

(a) forming a line in a first area of an internal layer, said line radiating unnecessary radiation;

(b) covering an upper surface of said internal layer with a first ground layer which disallows radiation to pass therethrough; and

(c) covering a lower surface of said internal layer with a second ground layer which disallows radiation to pass therethrough; ~~and~~

~~(d) forming a ground line in a second area except said first area in said internal layer.~~

**Claim 11 (Previously amended):** The method as set forth in claim 10, further comprising the step of forming a plurality of through-holes throughout said first ground layer, said internal layer, and said second ground layer.

**Claim 12 (Original):** The method as set forth in claim 10, further comprising the step of forming a plurality of through-holes throughout said first ground layer, said ground line, and said second ground layer so that said through-holes electrically connect said first ground layer, said ground line, and said second ground layer to one another.

**Claim 13 (Previously cancelled)**

**Claim 14 (Currently amended):** The cellular phone as set forth in claim 16, further comprising:

(f e) a first cover layer formed over a surface of said first ground layer; and

(g f) a second cover layer formed over a surface of said second

ground layer.

**Claim 15 (Original):** The cellular phone as set forth in claim 14, further comprising electrically insulating adhesive layers sandwiched among said internal layer, said first and second ground layers, and said first and second cover layers.

**Claim 16 (Currently amended):**

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A cellular phone including a flexible board, said flexible board comprising a ground line comprised of:

- (a) an internal layer;
- (b) a line formed in a first area of said internal layer, said line radiating unnecessary radiation;
- (c) a first ground layer formed on an upper surface of said internal layer, said first ground layer disallowing radiation to pass therethrough; and
- (d) a second ground layer formed on a lower surface of said internal layer, said second ground layer disallowing radiation to pass therethrough; and
- ~~(e) a ground line formed in a second area except said first area in said internal layer.~~

**Claim 17 (Previously amended):** The cellular phone as set forth in claim 16, wherein a plurality of through-holes is formed throughout said first ground layer, said internal layer, and said second ground layer.

**Claim 18 (Original):** The cellular phone as set forth in claim 16, wherein a plurality of through-holes is formed throughout said first ground

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layer, said ground line, and said second ground layer, said through-holes  
electrically connecting said first ground layer, said ground line, and said  
second ground layer to one another.

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